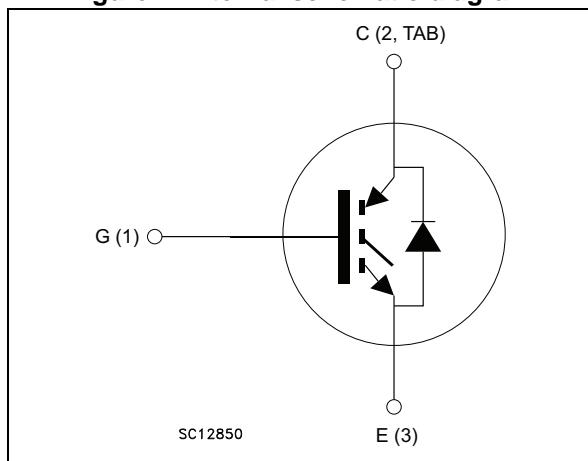


Figure 1. Internal schematic diagram



Features

- Maximum junction temperature: $T_J = 175 \text{ }^{\circ}\text{C}$
- High speed switching series
- Minimized tail current
- $V_{CE(\text{sat})} = 1.55 \text{ V (typ.)} @ I_C = 30 \text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- Very fast soft recovery antiparallel diode

Applications

- Photovoltaic inverters
- High frequency converters

Description

These devices are IGBTs developed using an advanced proprietary trench gate and field stop structure. The device is part of the new HB series of IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of any frequency converter. Furthermore, a slightly positive $V_{CE(\text{sat})}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1. Device summary

Order code	Marking	Package	Packaging
STGB30H60DFB	GB30H60DFB	D2PAK	Tape and reel
STGP30H60DFB	GP30H60DFB	TO-220	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curve)	6
3	Test circuits	12
4	Package information	13
4.1	D ² PAK package information	13
4.2	TO-220 package information	16
5	Packing information	18
6	Revision history	20

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600	V
I_C	Continuous collector current at $T_C = 25^\circ\text{C}$	60	A
I_C	Continuous collector current at $T_C = 100^\circ\text{C}$	30	A
$I_{CP}^{(1)}$	Pulsed collector current	120	A
I_F	Continuous forward current at $T_C = 25^\circ\text{C}$	60	A
I_F	Continuous forward current at $T_C = 100^\circ\text{C}$	30	A
$I_{FP}^{(1)}$	Pulsed forward current	120	A
V_{GE}	Gate-emitter voltage	± 20	V
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	260	W
T_{STG}	Storage temperature range	- 55 to 150	$^\circ\text{C}$
T_J	Operating junction temperature	- 55 to 175	$^\circ\text{C}$

1. Pulse width limited by maximum junction temperature.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.58	$^\circ\text{C}/\text{W}$
R_{thJC}	Thermal resistance junction-case diode	2.08	$^\circ\text{C}/\text{W}$
R_{thJA}	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

2 Electrical characteristics

$T_J = 25^\circ\text{C}$ unless otherwise specified.

Table 4. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ($V_{GE} = 0$)	$I_C = 2 \text{ mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$		1.55	2	V
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$ $T_J = 125^\circ\text{C}$		1.65		
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$ $T_J = 175^\circ\text{C}$		1.75		
V_F	Forward on-voltage	$I_F = 30 \text{ A}$		2	2.6	V
		$I_F = 30 \text{ A}; T_J = 125^\circ\text{C}$		1.7		
		$I_F = 30 \text{ A}; T_J = 175^\circ\text{C}$		1.6		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current ($V_{GE} = 0$)	$V_{CE} = 600 \text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current ($V_{CE} = 0$)	$V_{GE} = \pm 20 \text{ V}$			250	nA

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz},$ $V_{GE} = 0$	-	3659	-	pF
C_{oes}	Output capacitance		-	101	-	pF
C_{res}	Reverse transfer capacitance		-	76	-	pF
Q_g	Total gate charge	$V_{CC} = 520 \text{ V}, I_C = 30 \text{ A},$ $V_{GE} = 15 \text{ V}$, see Figure 29	-	149	-	nC
Q_{ge}	Gate-emitter charge		-	25	-	nC
Q_{gc}	Gate-collector charge		-	62	-	nC

Table 6. Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ see Figure 28	-	37	-	ns
t_r	Current rise time		-	14.6	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1643	-	A/ μs
$t_{d(off)}$	Turn-off delay time		-	146	-	ns
t_f	Current fall time		-	23	-	ns
E_{on}	Turn-on switching losses		-	383	-	μJ
$E_{off}^{(1)}$	Turn-off switching losses		-	293	-	μJ
E_{ts}	Total switching losses		-	676	-	μJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$, see Figure 28	-	35	-	ns
t_r	Current rise time		-	16.1	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1496	-	A/ μs
$t_{d(off)}$	Turn-off delay time		-	158	-	ns
t_f	Current fall time		-	65	-	ns
E_{on}	Turn-on switching losses		-	794	-	μJ
$E_{off}^{(1)}$	Turn-off switching losses		-	572	-	μJ
E_{ts}	Total switching losses		-	1366	-	μJ

1. Turn-off losses include also the tail of the collector current.

Table 7. Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, di/dt=1000 \text{ A}/\mu\text{s}, V_{GE} = 15 \text{ V},$ (see Figure 28)	-	53	-	ns
Q_{rr}	Reverse recovery charge		-	384	-	nC
I_{rrm}	Reverse recovery current		-	14.5	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	788	-	A/ μs
E_{rr}	Reverse recovery energy		-	104	-	μJ
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, di/dt=1000 \text{ A}/\mu\text{s}, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$, (see Figure 28)	-	104	-	ns
Q_{rr}	Reverse recovery charge		-	1352	-	nC
I_{rrm}	Reverse recovery current		-	26	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	310	-	A/ μs
E_{rr}	Reverse recovery energy		-	407	-	μJ

2.1 Electrical characteristics (curve)

Figure 2. Power dissipation vs. case temperature

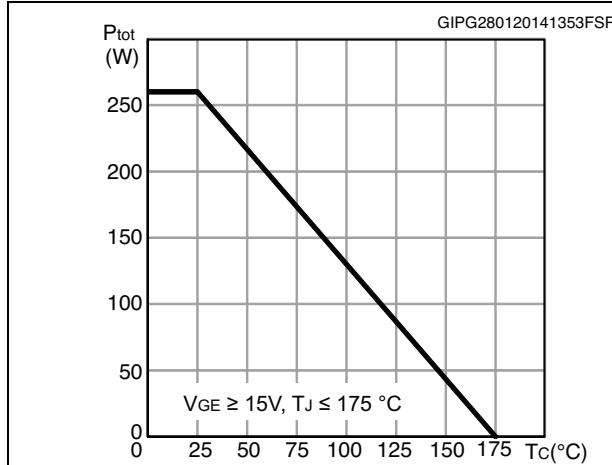


Figure 3. Collector current vs. case temperature

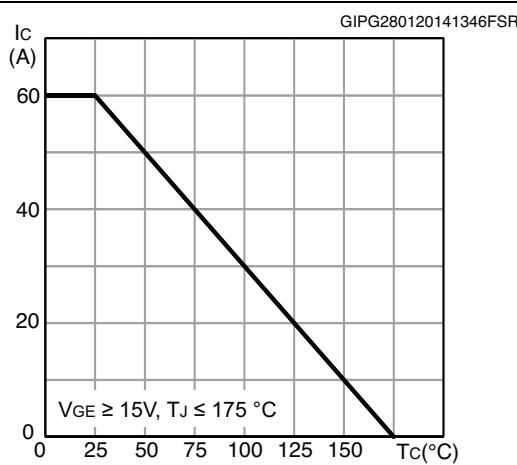


Figure 4. Output characteristics ($T_J = 25^{\circ}C$)

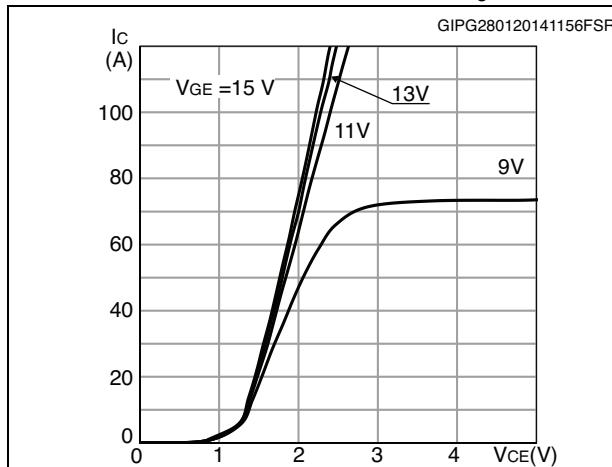


Figure 5. Output characteristics ($T_J = 175^{\circ}C$)

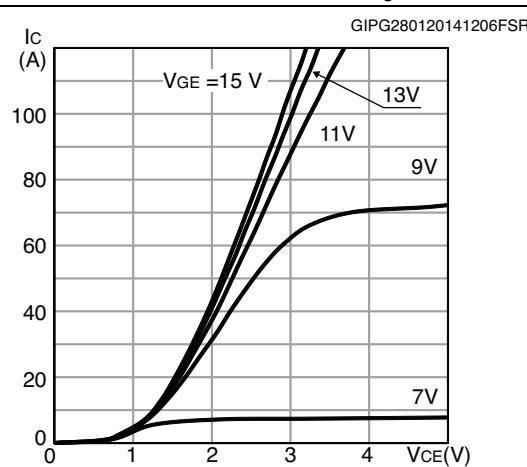


Figure 6. $V_{CE(sat)}$ vs. junction temperature

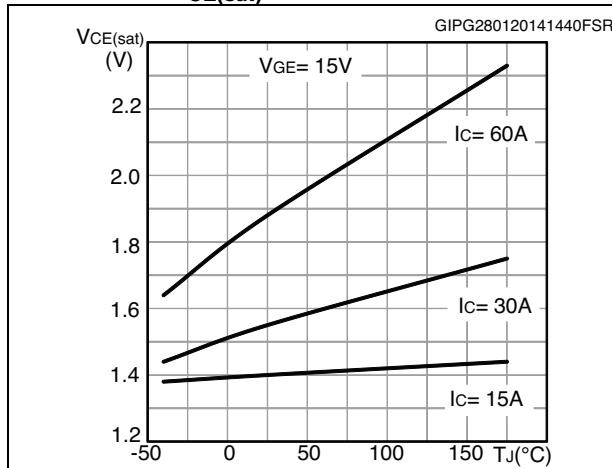


Figure 7. $V_{CE(sat)}$ vs. collector current

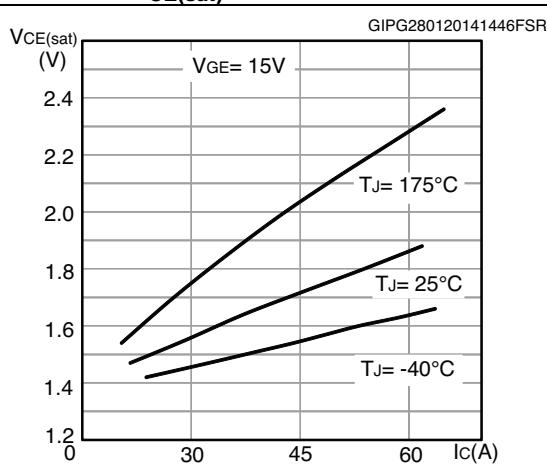


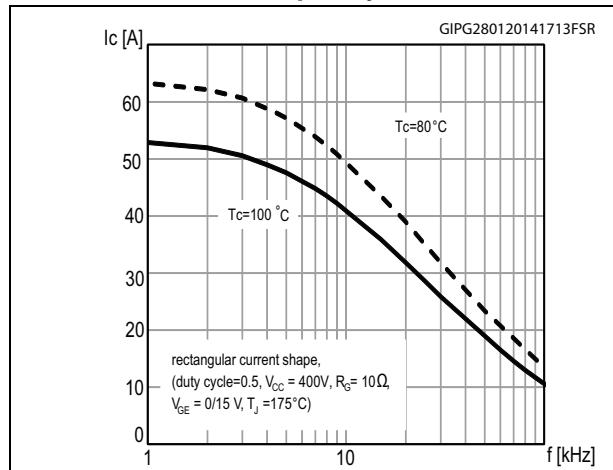
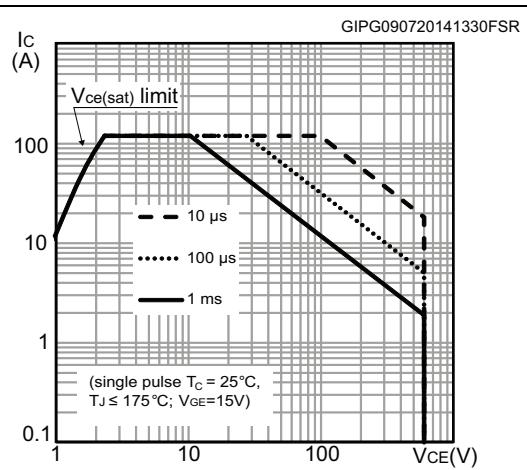
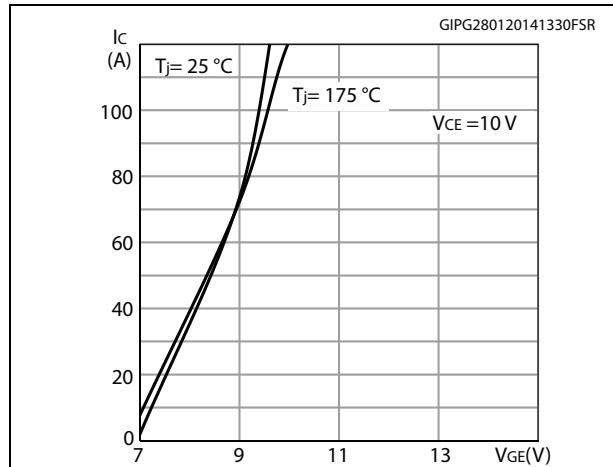
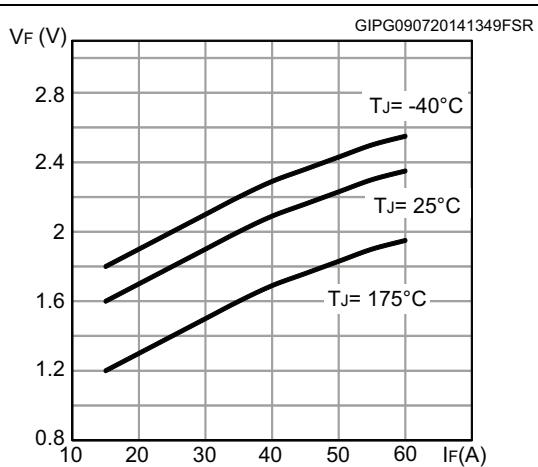
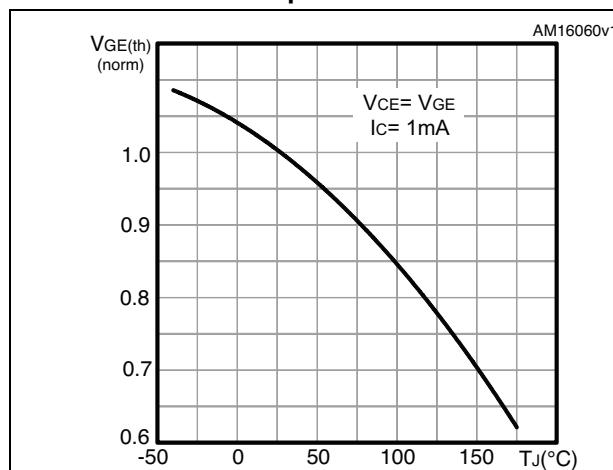
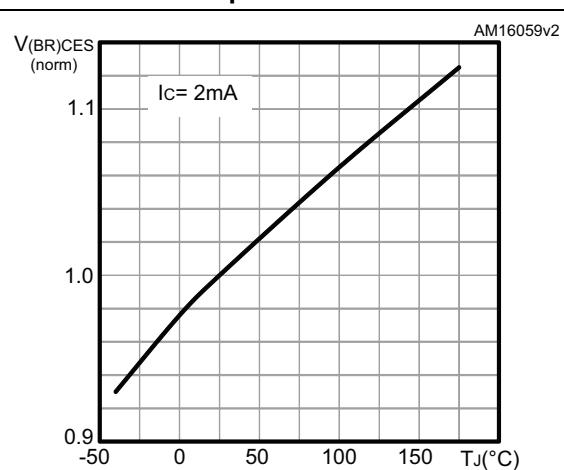
Figure 8. Collector current vs. switching frequency**Figure 9. Forward bias safe operating area****Figure 10. Transfer characteristics****Figure 11. Diode V_F vs. forward current****Figure 12. Normalized $V_{GE(th)}$ vs junction temperature****Figure 13. Normalized $V_{(BR)CES}$ vs. junction temperature**

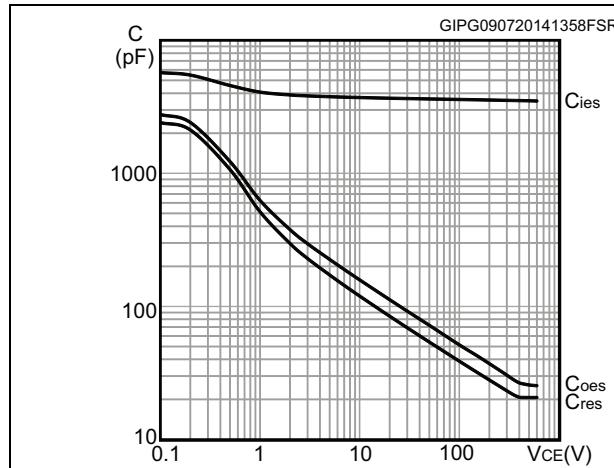
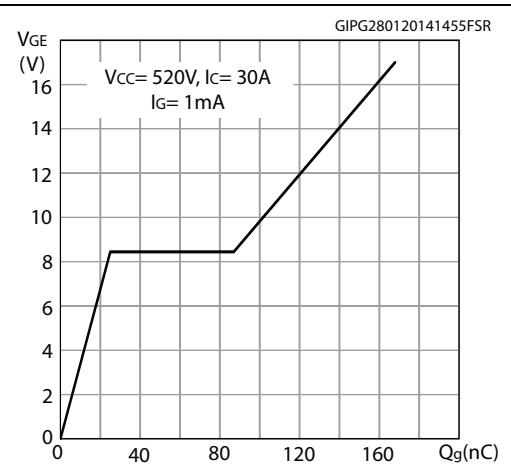
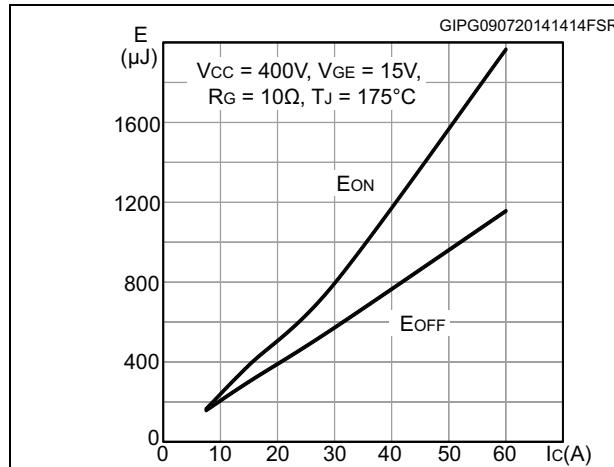
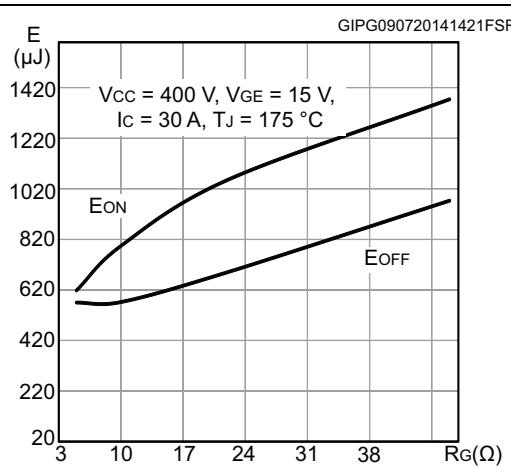
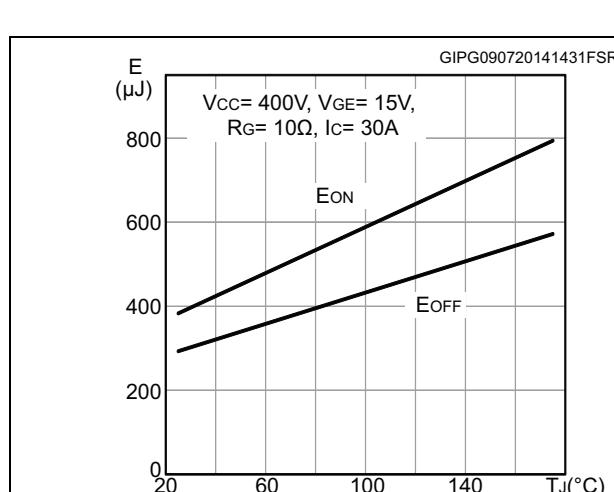
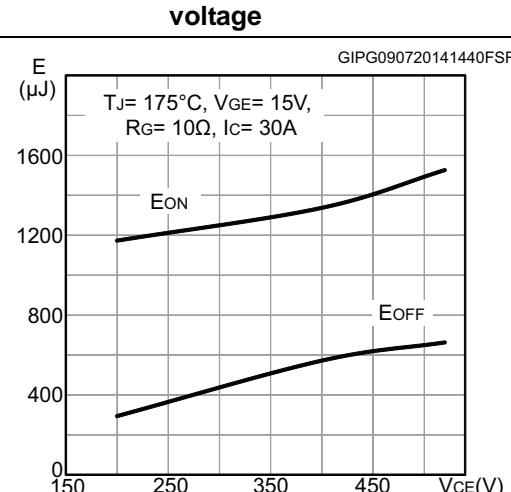
Figure 14. Capacitance variation**Figure 15. Gate charge vs. gate-emitter voltage****Figure 16. Switching loss vs collector current****Figure 17. Switching loss vs gate resistance****Figure 18. Switching loss vs temperature****Figure 19. Switching loss vs collector-emitter voltage**

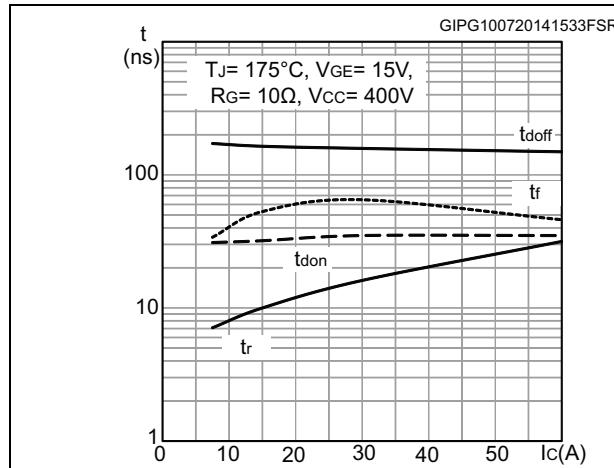
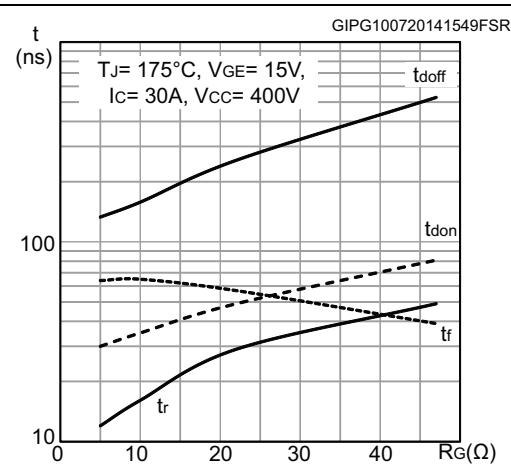
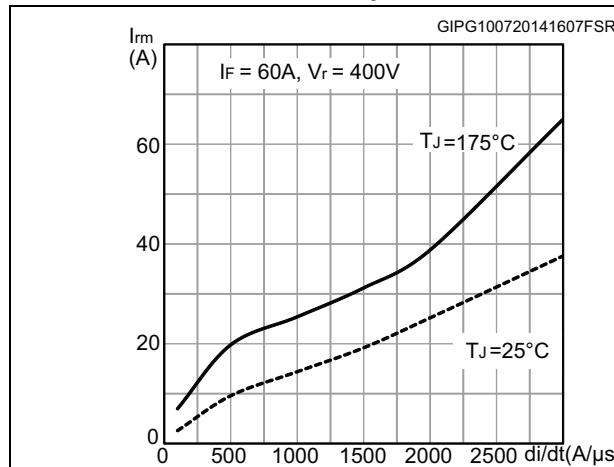
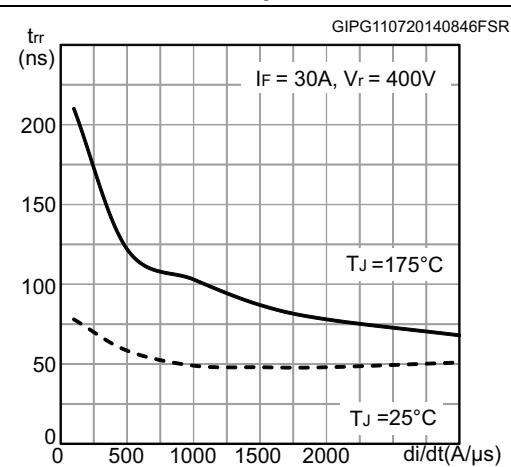
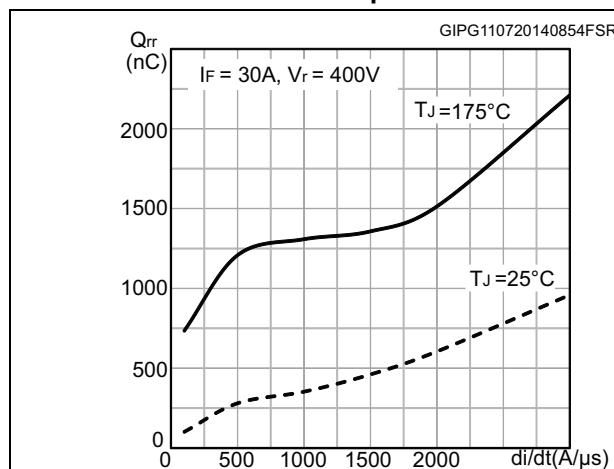
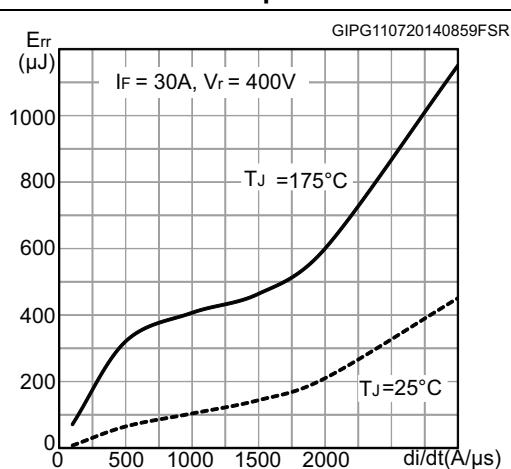
Figure 20. Switching times vs. collector current**Figure 21. Switching times vs. gate resistance****Figure 22. Reverse recovery current vs. diode current slope****Figure 23. Reverse recovery time vs. diode current slope****Figure 24. Reverse recovery charge vs. diode current slope****Figure 25. Reverse recovery energy vs. diode current slope**

Figure 26. Thermal impedance for IGBT

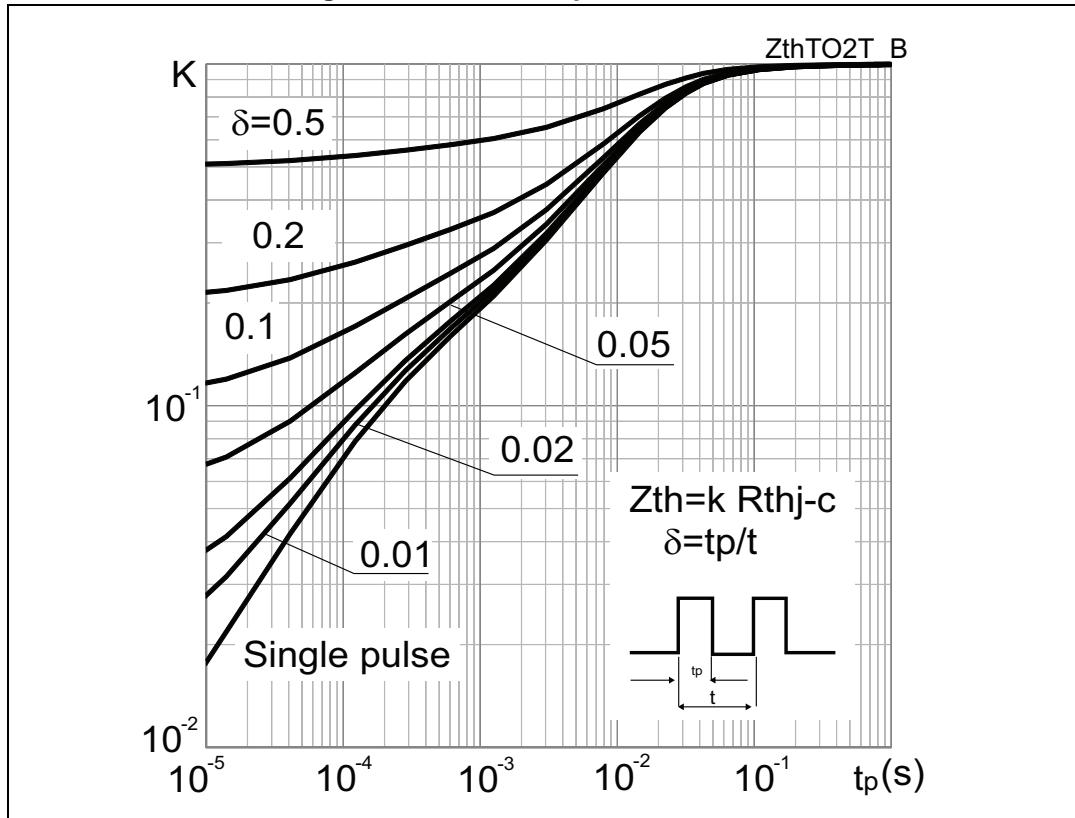
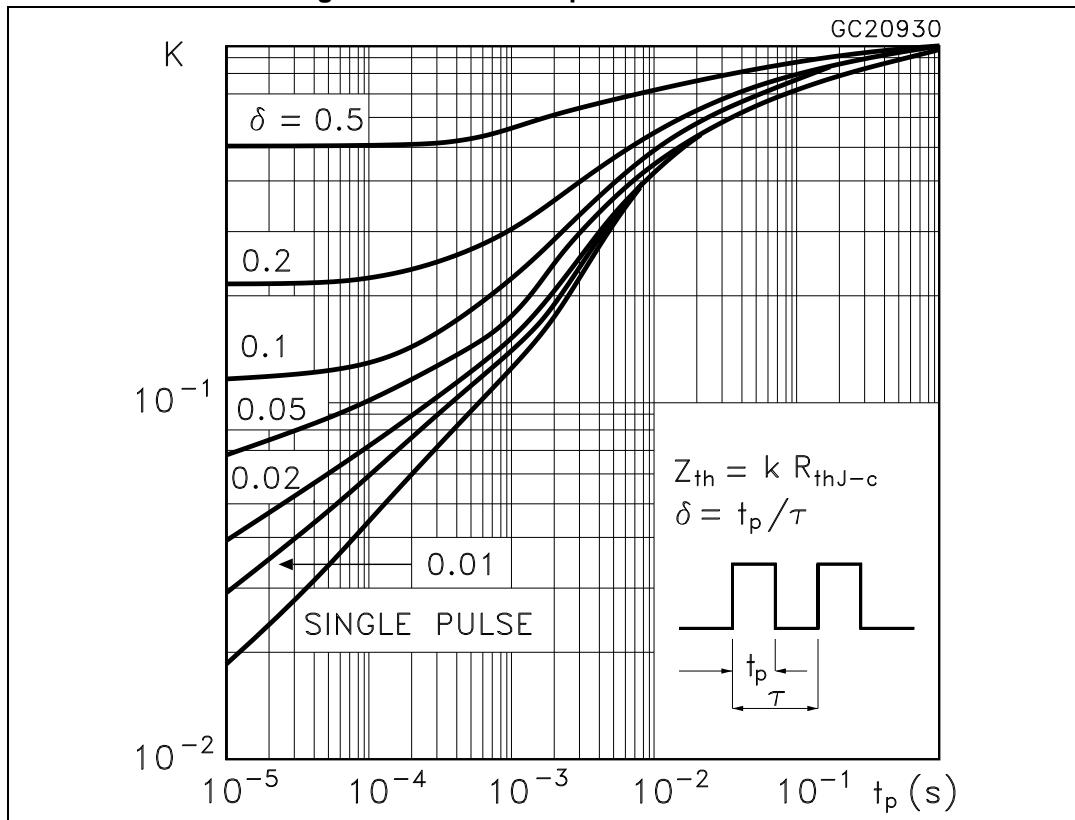


Figure 27. Thermal impedance for diode



3 Test circuits

Figure 28. Test circuit for inductive load switching

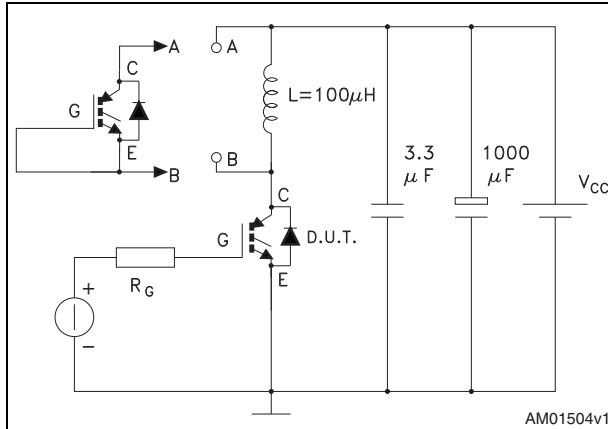


Figure 29. Gate charge test

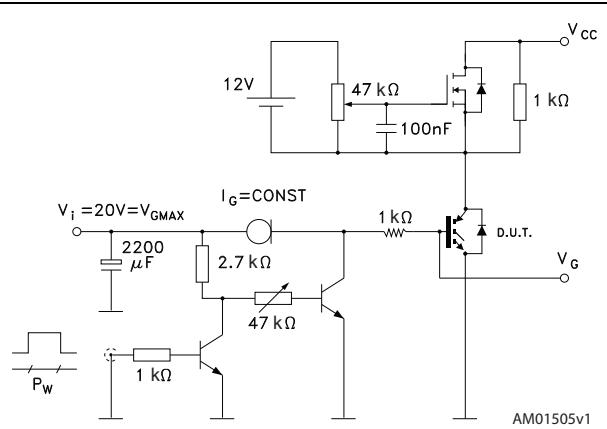


Figure 30. Switching waveform

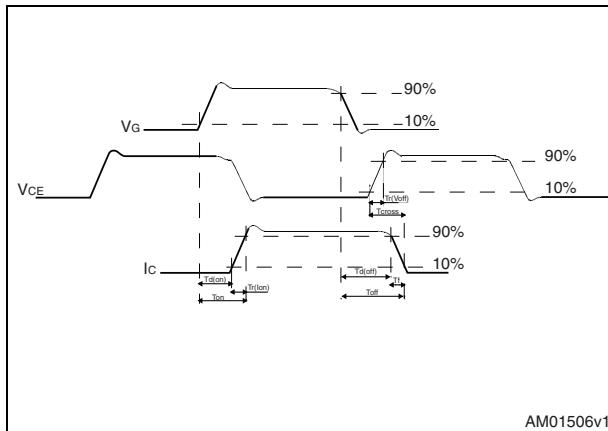
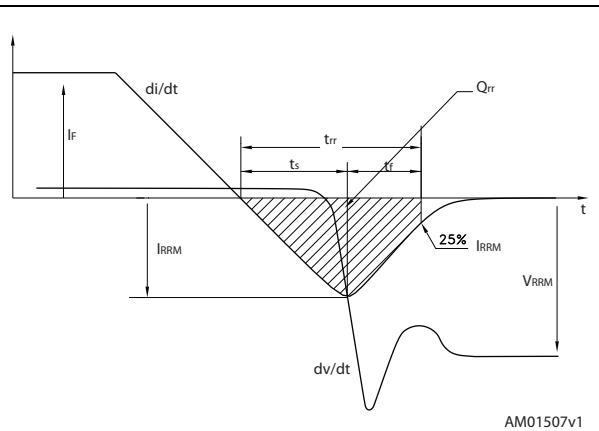


Figure 31. Diode reverse recovery waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK is an ST trademark.

4.1 D²PAK package information

Figure 32. D²PAK (TO-263) type A package outline

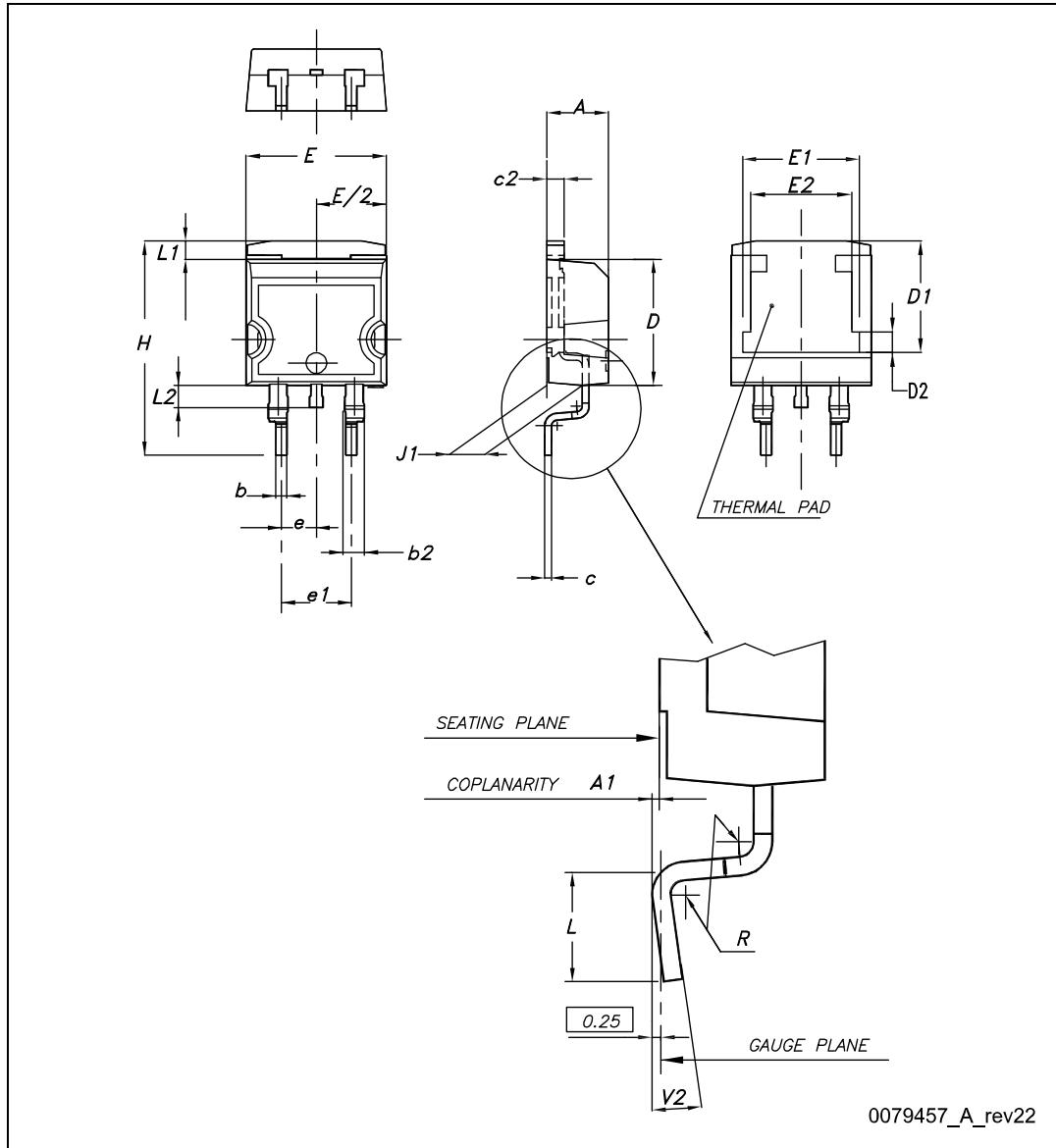
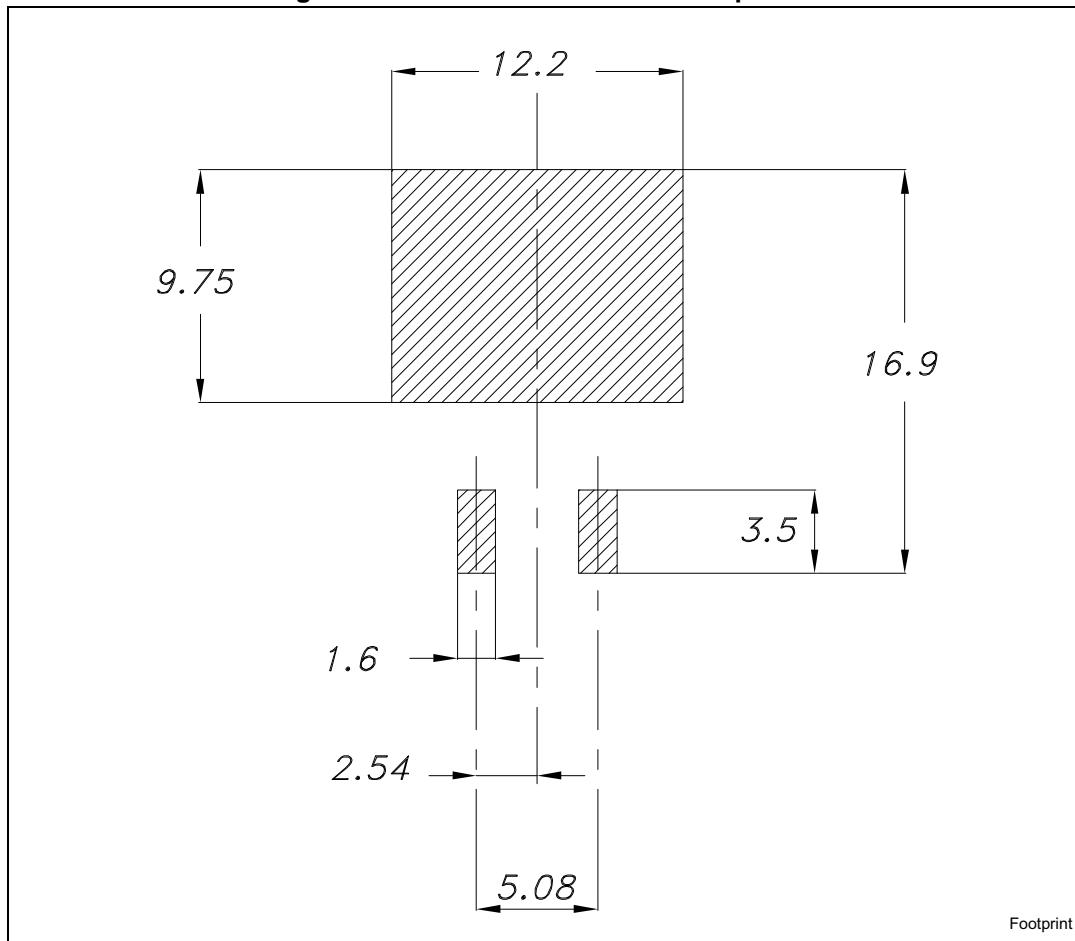


Table 8. D²PAK (TO-263) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 33. D²PAK recommended footprint^(a)

Footprint

a. All dimension are in millimeters

4.2 TO-220 package information

Figure 34. TO-220 type A package outline

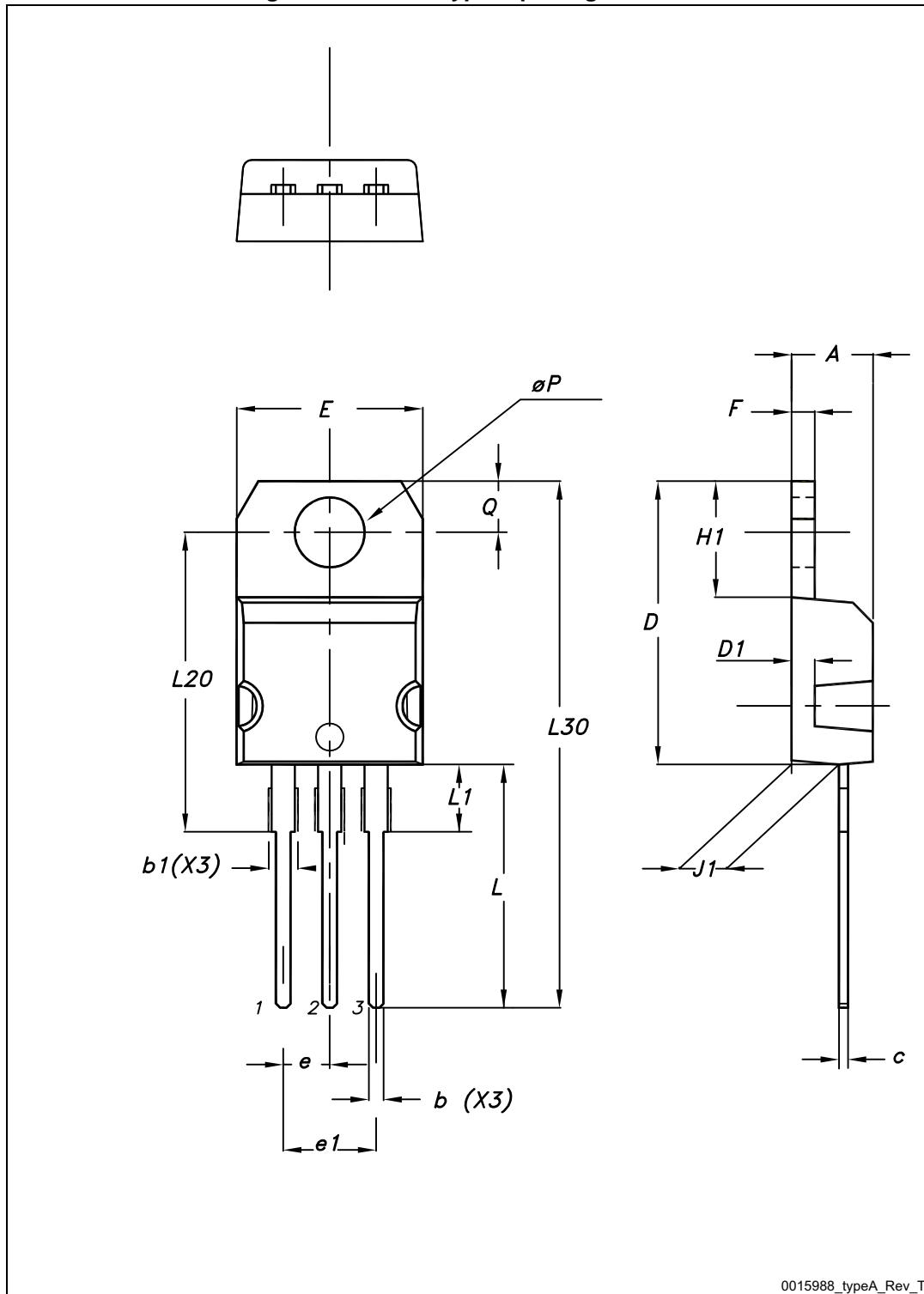


Table 9. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Packing information

Figure 35. Tape

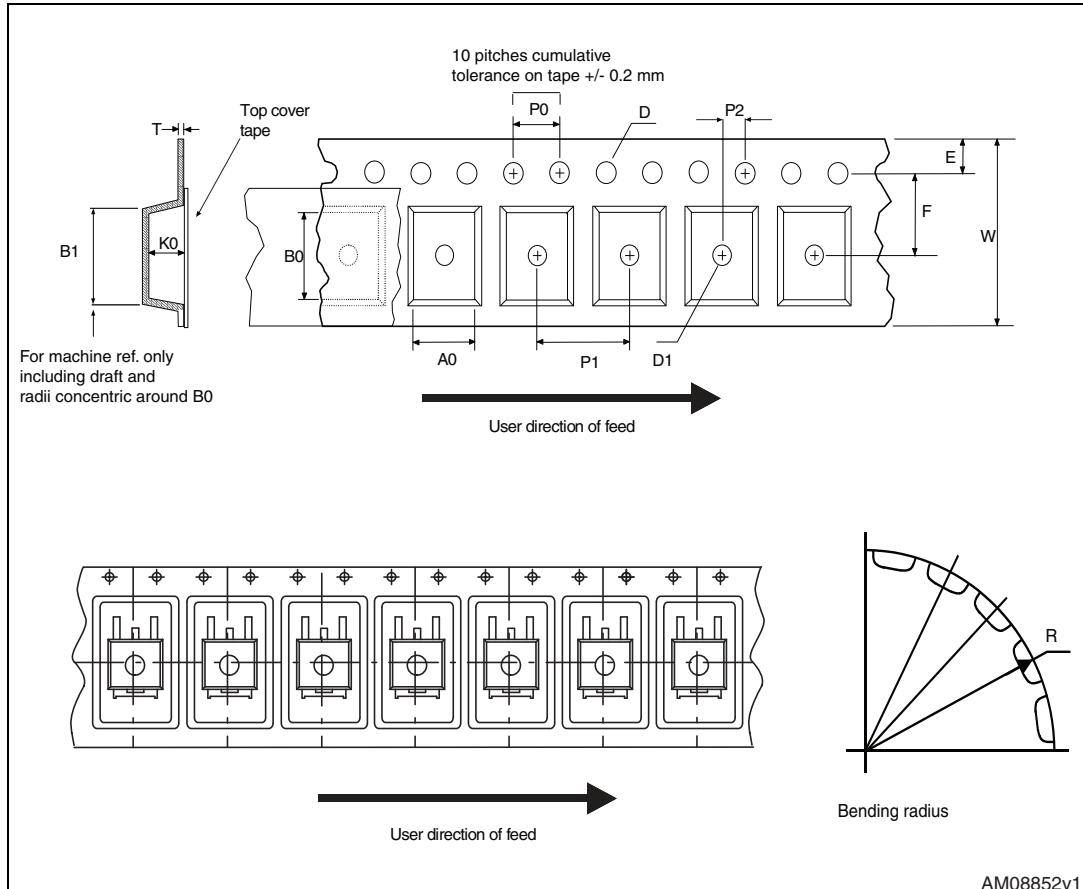
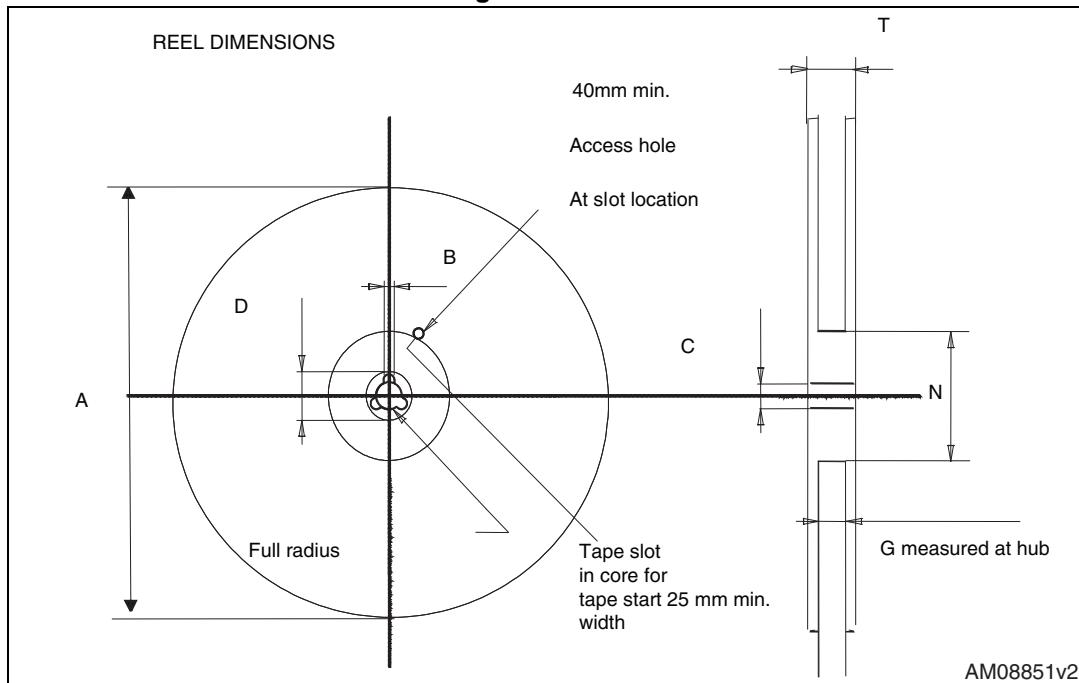


Figure 36. Reel

Table 10. D²PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

6 Revision history

Table 11. Document revision history

Date	Revision	Changes
07-Aug-2014	1	Initial release.
28-Oct-2015	2	Updated <i>Figure 23</i> and <i>Section 5</i> . Minor text changes.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2015 STMicroelectronics – All rights reserved